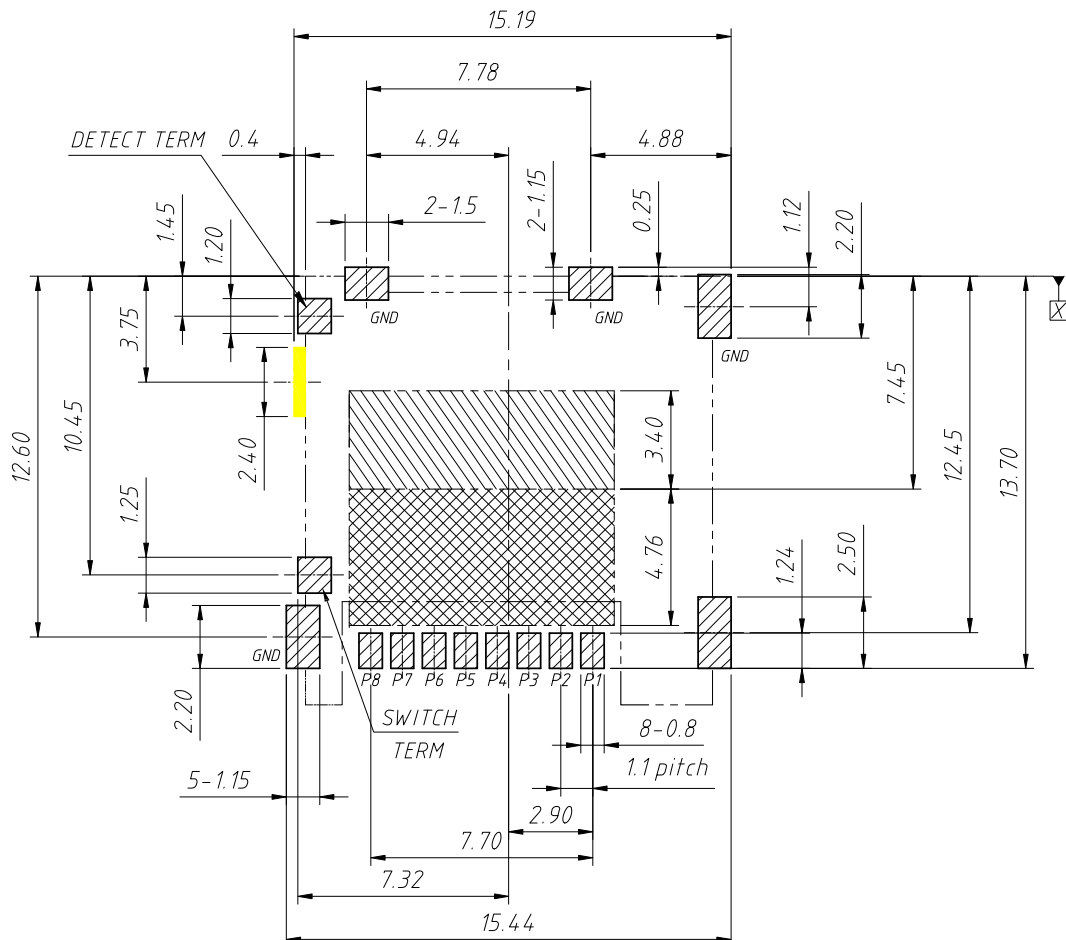


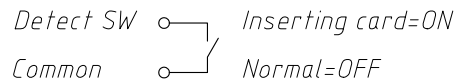
GENERAL TOLERANCE		ANGLE TOLERANCE		PROJECTION		Description:	
X	±0.15	X	±5°	UNITS		Micro SD Card CONN;PUSH/ PUSH,H1.4mm,SMD with CD Pin L-KLS1-TF-016	
.X	±0.03	.X	±3°	SHEET SIZE	A4		
.XX	±0.05	.XX	±2°	KLSP/N:			
Draw by:	Jenny	Date:	2018-03-10			NingBo KLS ELECTRONIC CO.,L TD.	
Check by:		Date:	2018-03-10				
SCALE		SHEET	1 OF 1				



RECOMMENDED PCB LAYOUT
TOLERANCE UNLESS OTHERWISE IS ± 0.05

- PROHIBITED AREA
- SOLDER PROHIBITED AREA
- PATTERN PROHIBITED AREA
- PAD AREA

Circuit diagram for detect switch



PIN NO.	DISCRIPTION
Pin 1	DAT2:Data line
Pin 2	CD/DAT3:Card Detect/Data line
Pin 3	CMD:Command/Response
Pin 4	VDD:Supply voltage
Pin 5	CLK:Clock
Pin 6	VSS:Supply voltage ground
Pin 7	DAT0:Data line
Pin 8	DAT1:Data line
GND	Cover GND
Switch term	Detect SW(CD)
Detect term	Detect SW(GND)

1. Material :

- 1.1 Insulator:High Temperature Thermoplastic,(LCP,MG350),UL Black 94V-0.
- 1.2 Contact: Phosphor Bronze(C5210R-H,T=0.15 \pm 0.03mm)
- 1.3 Shell: SUS304-H T=0.12 \pm 0.03mm

2.Plating:

- 2.1 Contact: Plated 50u"min Ni Overall,Plated 1u"min Au Selective contact area, Plated 100u"min Sn over Ni on solder area.
- 2.2 Shell: Plated 50u"min Ni Overall,Plated 1u"min Au Selective Contact Area

3.Property:

- 3.1 Current Rating :0.5A AC/DC max.
- 3.2 Voltage Rating :3.3V/5V(AC/DC)
- 3.3 Contact Resistance:Contact Pin 100m Ω max.
- 3.4 Insert/Pulling Force: 40N Max / 0.5~40N
- 3.5 Smt Solder Temperature: Should Under 260 $^{\circ}$ C
- 3.6 Operation Temperature Range: -40~+85 $^{\circ}$ C

GENERAL TOLERANCE		ANGLE TOLERANCE		PROJECTION	Description:	
X	± 0.15	X	$\pm 5^{\circ}$		Micro SD Card CONN;PUSH/ PUSH,H1.4mm,SMD with CD Pin	
.X	± 0.03	.X	$\pm 3^{\circ}$	UNITS		mm
.XX	± 0.05	.XX	$\pm 2^{\circ}$	SHEET SIZE		A4
SCALE				KLS P/N:		L-KLS1-TF-016
Draw by:	Jenny	Date:	2018-03-10	NingBo KLS ELECTRONIC CO.,L TD.		
Check by:		Date:	2018-03-10			
SHEET		1	OF	1		